

Transistors

10V Drive Nch MOS FET

RDN050N20**●Structure**

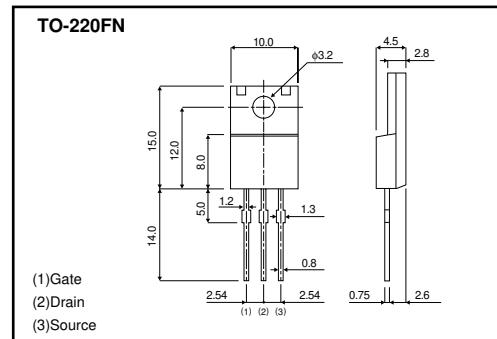
Silicon N-channel
MOS FET

●Features

- 1) Low on-resistance.
- 2) Low input capacitance.
- 3) Excellent resistance to damage from static electricity.

●Application

Switching

●External dimensions (Unit : mm)**●Packaging specifications**

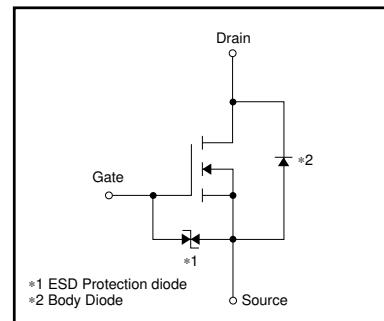
| Type | Package | Bulk |
|-----------|---------|------|
| | Code | - |
| RDN050N20 | | 500 |

●Absolute maximum ratings (Ta=25°C)

| Parameter | Symbol | Limits | Unit |
|--|--------------------|---------------------|------|
| Drain-Source Voltage | V _{DSS} | 200 | V |
| Gate-Source Voltage | V _{GSS} | ±30 | V |
| Drain Current | Continuous | I _D | A |
| | Pulsed | I _{DP} *1 | 20 |
| Reverse Drain Current | Continuous | I _{DR} | A |
| | Pulsed | I _{DRP} *1 | 20 |
| Source Current (Body Diode) | Continuous | I _S | A |
| | Pulsed | I _{SP} *1 | 20 |
| Avalanche Current | I _{AS} *2 | 5 | A |
| Avalanche Energy | E _{AS} *2 | 75 | mJ |
| Total Power Dissipation (T _c =25°C) | P _D | 30 | W |
| Channel Temperature | T _{ch} | 150 | °C |
| Storage Temperature | T _{stg} | -55 to +150 | °C |

*1 P_w ≤ 10μs, Duty cycle ≤ 1%

*2 L = 4.5mH, V_{DD}=50V, R_G=25Ω, 1Pulse, T_{ch}=25°C

●Equivalent Circuit

*1 ESD Protection diode
*2 Body Diode

A protection diode is included between the gate and source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

●Thermal resistance

| Parameter | Symbol | Limits | Unit |
|--------------------|-----------------------|--------|------|
| Channel to case | R _{th(ch-c)} | 4.17 | °C/W |
| Channel to ambient | R _{th(ch-a)} | 62.5 | °C/W |

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●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions | |
|---|-----------------------|------|------|------|------|--|---|
| Gate-Source Leakage | I _{GSS} | — | — | ±10 | µA | V _{GS} =±30V, V _{DS} =0V | |
| Drain-Source Breakdown Voltage | V _{(BR) DSS} | 200 | — | — | V | I _D =250µA, V _{GS} =0V | |
| Zero Gate Voltage Drain Current | I _{DS} | — | — | 25 | µA | V _{DS} =200V, V _{GS} =0V | |
| Gate Threshold Voltage | V _{GS (th)} | 2.0 | — | 4.0 | V | V _{DS} =10V, I _D =1mA | |
| Static Drain-Source On-State Resistance | R _{DS (on)} | * | — | 0.55 | 0.72 | Ω | I _D =2.5A, V _{GS} =10V |
| Forward Transfer Admittance | Y _{fs} | * | 1.1 | 1.8 | — | S | V _{DS} =10V, I _D =2.5A |
| Input Capacitance | C _{iss} | — | 292 | — | pF | V _{DS} =10V | |
| Output Capacitance | C _{oss} | — | 92 | — | pF | V _{GS} =0V | |
| Reverse Transfer Capacitance | C _{rss} | — | 28 | — | pF | f=1MHz | |
| Turn-On Delay Time | t _{d (on)} | * | — | 10 | — | ns | I _D =2.5A, V _{DD} =100V |
| Rise Time | t _r | * | — | 22 | — | ns | V _{GS} =10V |
| Turn-Off Delay Time | t _{d (off)} | * | — | 23 | — | ns | R _L =40Ω |
| Fall Time | t _f | * | — | 28 | — | ns | R _G =10Ω |
| Total Gate Charge | t _{rr} | * | — | 9.3 | 18.6 | nC | V _{DD} =100V |
| Gate-Source Charge | Q _{rr} | * | — | 2.8 | — | nC | V _{GS} =10V |
| Gate-Drain Charge | Q _g | * | — | 3.7 | — | nC | I _D =5A |

* Pulsed

●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-------------------------|-----------------|------|------|------|------|--|
| Forward voltage | V _{SD} | * | — | 2.0 | V | I _S = 2.5A, V _{GS} =0V |
| Reverse recovery time | t _{rr} | * | — | 117 | — | ns |
| Reverse recovery charge | Q _{rr} | * | — | 0.37 | — | µC |

* Pulsed

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● Electrical characteristic curves

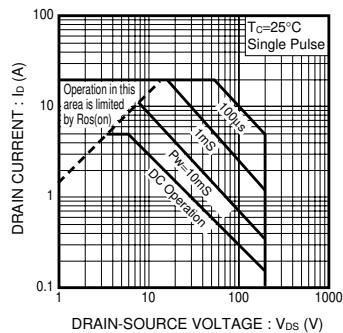


Fig.1 Maximum Safe Operating Area

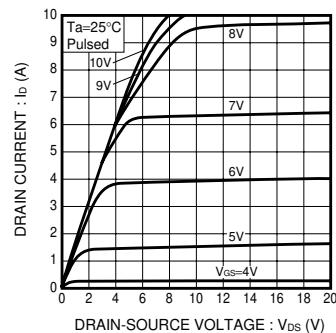


Fig.2 Typical Output Characteristics

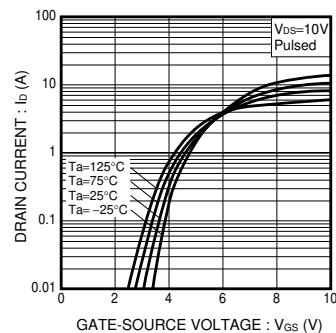


Fig.3 Typical Transfer Characteristics

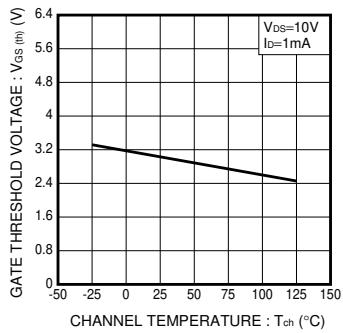


Fig.4 Gate Threshold Voltage vs. Channel Temperature

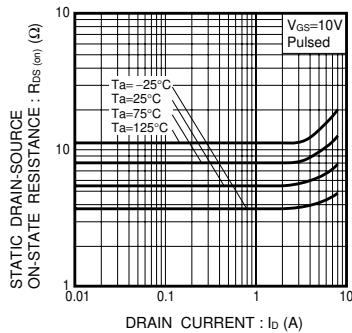


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

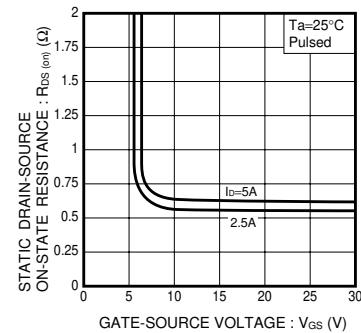


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

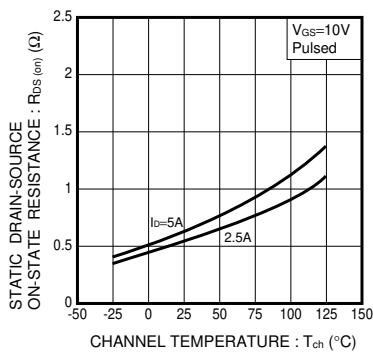


Fig.7 Static Drain-Source On-State Resistance vs. Channel Temperature

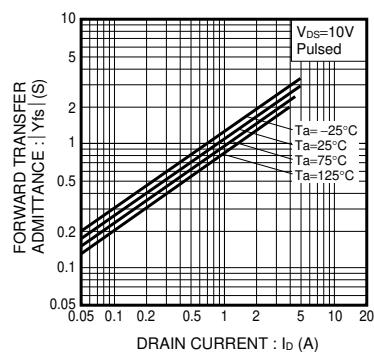


Fig.8 Forward Transfer Admittance vs. Drain Current

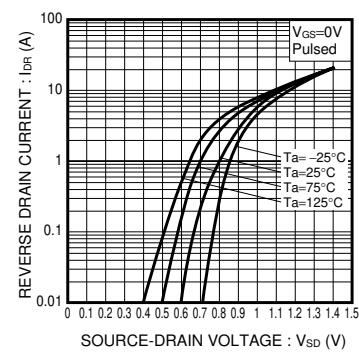


Fig.9 Reverse Drain Current vs. Source-Drain Voltage

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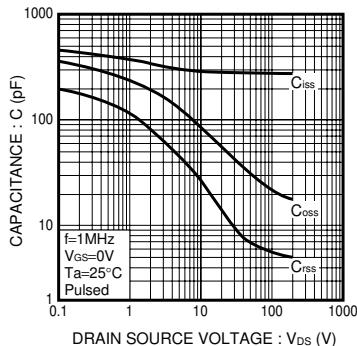
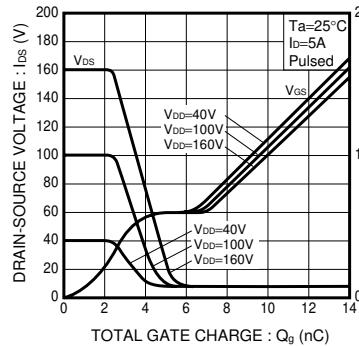
Fig.10 Typical Capacitance vs.
Drain-Source Voltage

Fig.11 Dynamic Input Characteristics

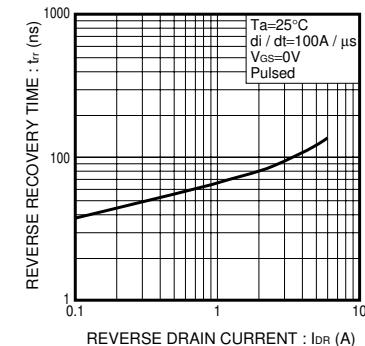
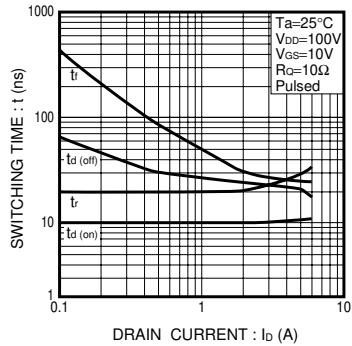
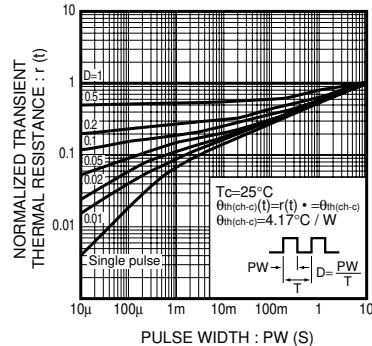
Fig.12 Reverse Recovery Time
vs. Reverse Drain Current

Fig.13 Switching Characteristics

Fig.14 Normalized Transient
Thermal Resistance vs.
Pulse Width

Appendix

Notes

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